

# 2022 IEEE/ASME International Conference on Advanced Intelligent Mechatronics

July 11th- 15th, 2022 | Royton Sapporo, Sapporo, Hokkaido, Japan

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Contact Us AIM2022 Secretariat c/o JTB Communication Design, Inc. Email: aim2022@jtbcom.co.jp



# **Call for Papers**

The 2022 IEEE/ASME International Conference on Advanced Intelligent Mechatronics (AIM 2022) will be held on July 11 -15,

2022 in Royton Sapporo, Sapporo, Japan. As a flagship conference focusing on mechatronics and intelligent systems, the AIM 2022 will bring together an international community of experts to discuss the state-of-the-art, new research results, perspectives of future developments, and innovative applications relevant to mechatronics, robotics, automation, industrial electronics, and related areas.

The sponsors and organizers of AIM 2022 invite a submission of high quality mechatronics research papers describing original work, including but not limited to the following topics:

Actuators, Automotive Systems, Bioengineering, Data Storage Systems, Electronic Packaging, Fault Diagnosis, Human-Machine

interfaces, Human-Robot Interaction/Collaboration, Human Factors in Mechatronics Systems, Industry Applications, Information Technology, Intelligent Systems, Machine Vision, Manufacturing, Micro-Electro-Mechanical Systems, Micro/Nano Technology, Modeling and Design, System Identification and Adaptive Control, Motion Control, Vibration and Noise Control, Neural and Fuzzy Control, Opto-Electronic Systems, Optomechatronics, Prototyping, Real-Time and Hardware-in-the-Loop Simulation, Robotics, Sensors, System Integration, Transportation Systems, Smart Materials and Structures, Energy Harvesting, and other frontier fields.

All contributed and invited papers, tutorial and workshop proposals, and invited and special session proposals must be uploaded through the submission website (www.aim2022.org) according to the deadlines below.

# **Contributed & Invited Papers:**

All papers go through a rigorous review process. Accepted papers will be presented by their authors at the conference. All accepted peer-reviewed manuscripts will be published in the conference proceedings, and will be submitted for inclusion in IEEEXplore, subject to formatting and copyright requirements.

# Tutorials & Workshops:

Proposals are invited for half-day or full-day tutorials and workshops.

Workshops explore the frontiers of recent or emerging topics in mechatronics, while tutorials provide a foundation for future self-study in important area of mechatronics. Tutorial and workshop proposals must include: (1) a statement of objectives, (2) a description of the intended audience, and (3) a list of speakers with an outline of their planned presentations. Unless specifically requested, individual tutorial and workshop presentations are not peer reviewed, and do not appear in the proceedings.

# Invited & Special Sessions:

Proposals are invited for invited and special sessions. Invited sessions consist of 4 to 6 thematically related invited papers. Invited session proposals consist of a brief statement of purpose and extended abstracts of the included invited papers. Invited papers are submitted and reviewed following the same process as contributed papers, and are included in the proceedings. **TMECH/AIM Focused Section Papers** 

Submissions to the Third Edition of the Focused Section on TMECH/AIM Emerging Topics are done through the TMECH site. Accepted TMECH/AIM Focused Section papers will be presented at AIM 2022 and published in the Third Edition of TMECH/AIM Focused Section in the August Issue of TMECH in 2022. The publication in the dedicated Issue of TMECH, however, will be subject to the presentation of the paper at AIM 2022 with paid registration fee. Papers rejected for publication in TMECH will still be considered by the Program Committee of AIM 2022, which makes a final acceptance/rejection decision for AIM 2022.

# **Important Dates**

Submission of Special & Invited Session Proposals: Submission of Tutorial & Workshop Proposals: Submission of Contributed & Invited Papers: Notification of Paper Status: Final paper Submission:





February 10, 2022 February 10, 2022 February 25, 2022 May 2, 2022 May 16, 2022

